



GP
ELECTRONICS

GPT064N20NTD
200V N-Channel MOSFET

Product Summary

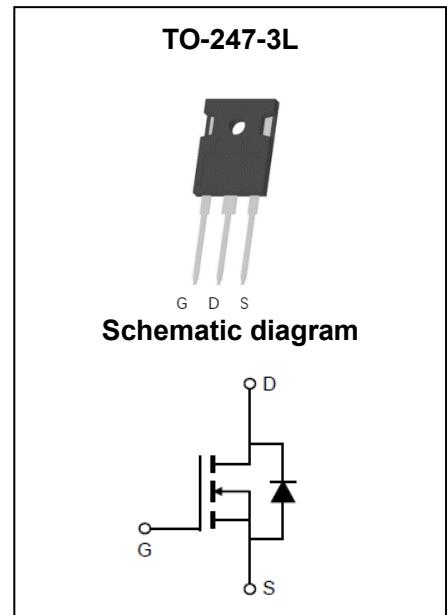
$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
200V	6.4mΩ@10V	135A

Feature

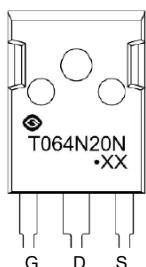
- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- DC/DC Converter
- Power Switching Application



MARKING:



T064N20N = Device Code

XX = Date Code

Solid Dot = Green Indicator

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

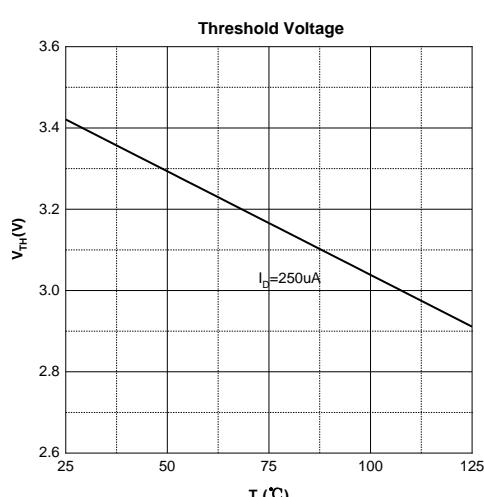
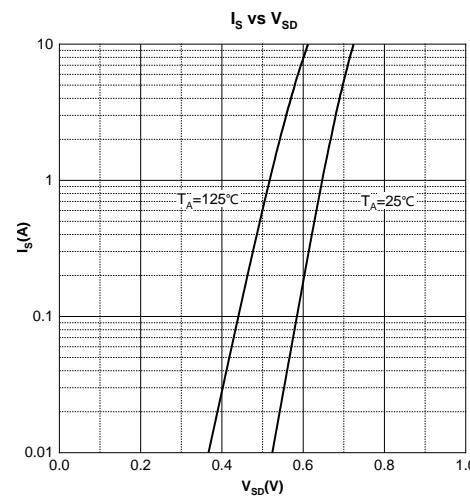
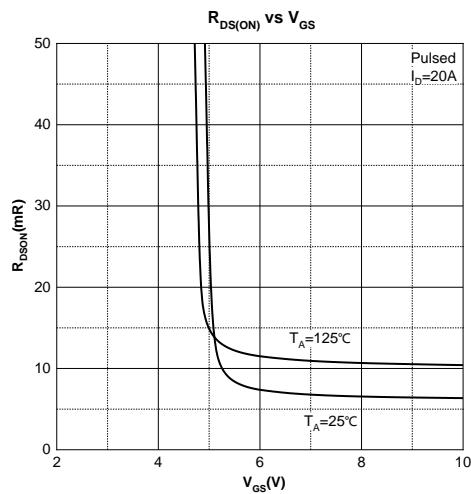
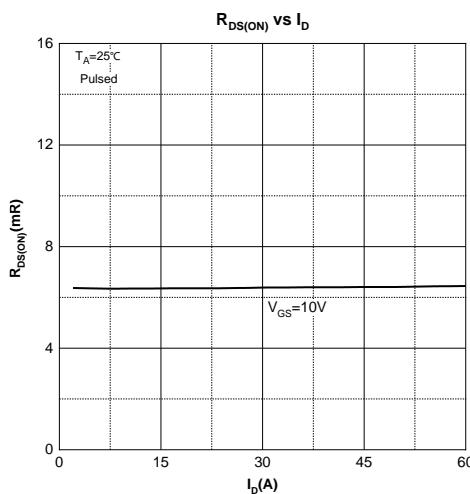
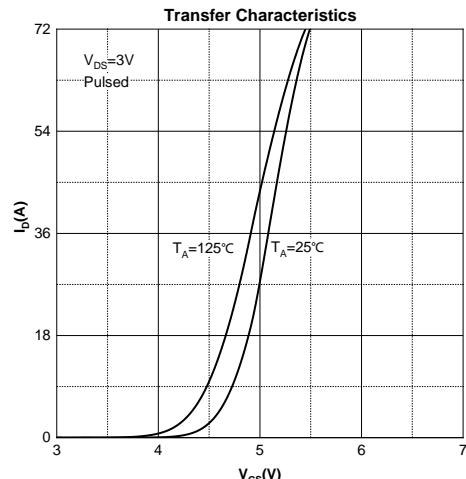
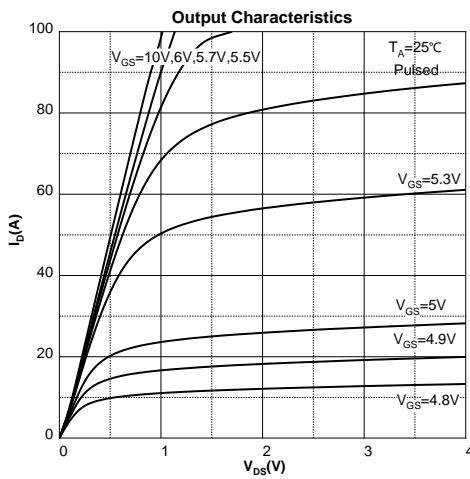
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	200	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	135	A
	I_D	88	A
Pulsed Drain Current ²	I_{DM}	540	A
Single Pulsed Avalanche Current ³	I_{AS}	93	A
Single Pulsed Avalanche Energy ³	E_{AS}	2162	mJ
Power Dissipation ⁵	P_D	368	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	49	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.34	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

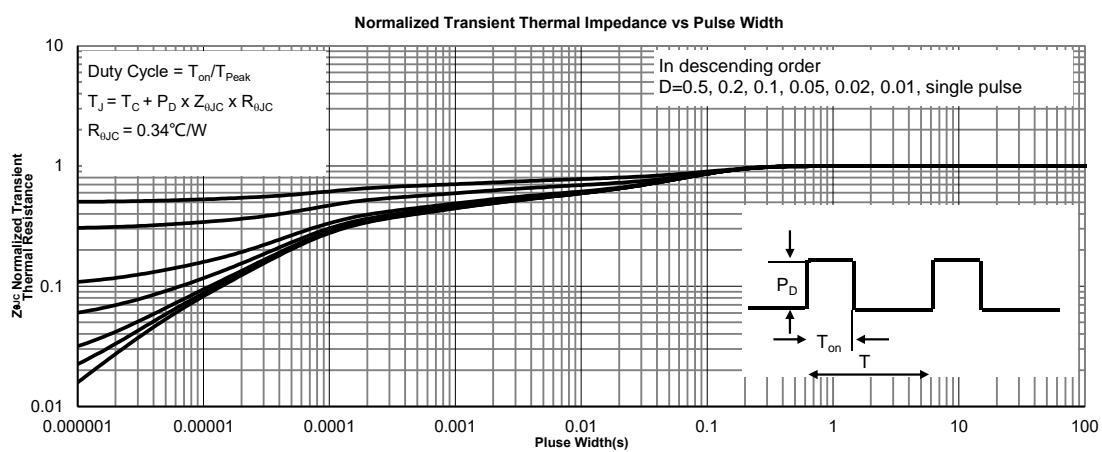
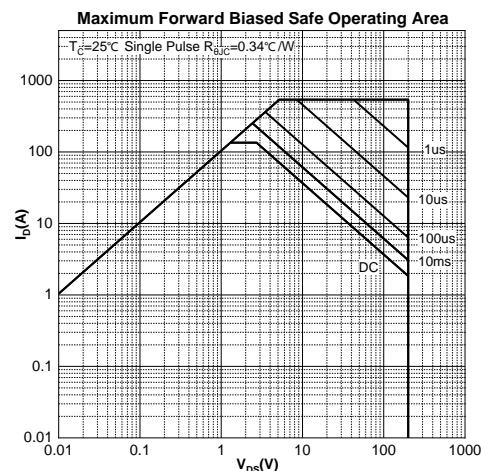
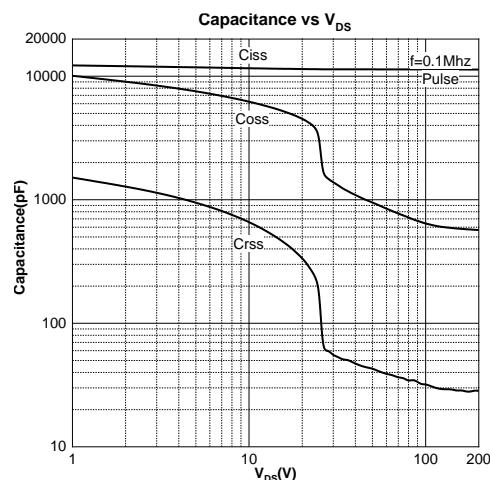
MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

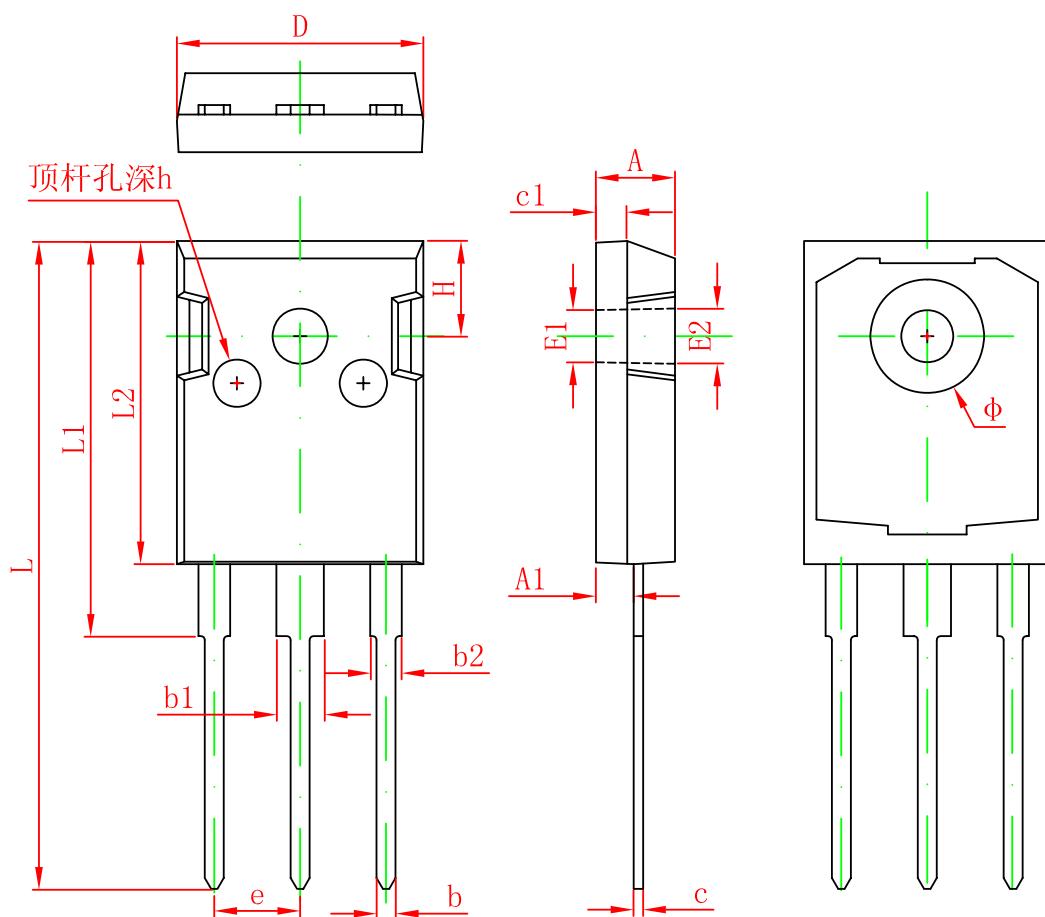
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	200			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 200\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3.4	4	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		6.4	8.3	$\text{m}\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 0.1\text{MHz}$		11375		pF
Output Capacitance	C_{oss}			638		
Reverse Transfer Capacitance	C_{rss}			35		
Gate Resistance	R_g	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 0.1\text{MHz}$		1.6		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 100\text{V}, V_{GS} = 10\text{V}, I_D = 20\text{A}$		160		nC
Gate-source Charge	Q_{gs}			54		
Gate-drain Charge	Q_{gd}			34		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 100\text{V}, V_{GS} = 10\text{V}, I_D = 20\text{A}, R_G = 4.7\Omega$		51		ns
Turn-on Rise Time	t_r			34		
Turn-off Delay Time	$t_{d(off)}$			62		
Turn-off Fall Time	t_f			13		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0\text{V}, I_S = 20\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{DD} = 100\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics




TO-247-3L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	
h	0.000	0.300	0.000	0.012